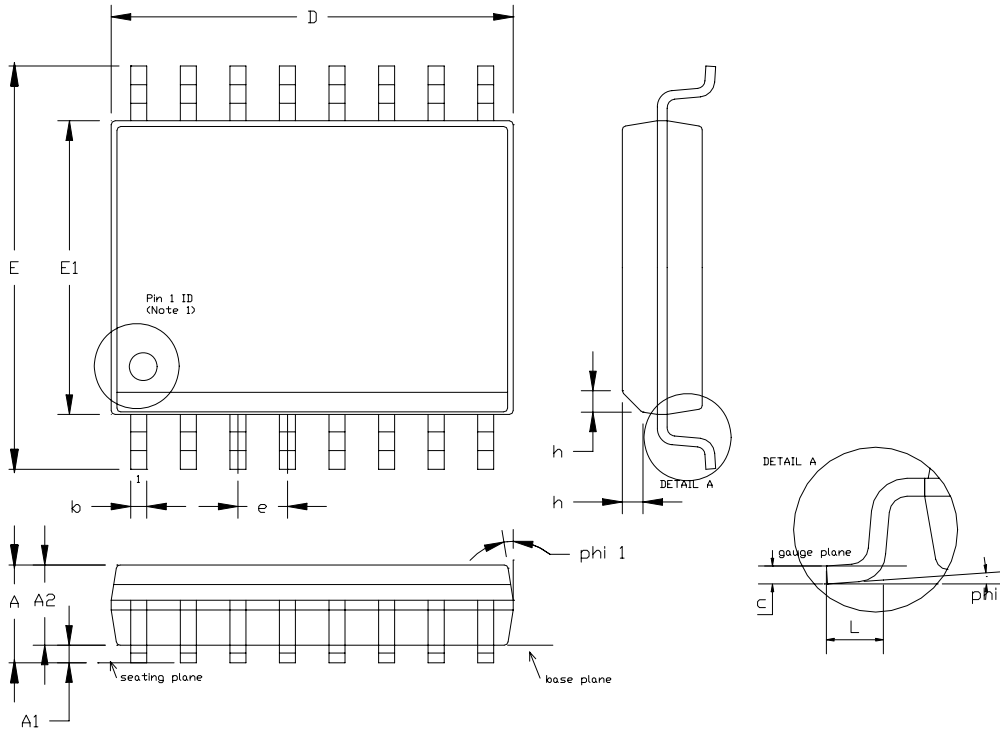


| | | |
|------------------|---|-----------------------------|
| Date: 05.02.2013 | PACKAGE OUTLINE SPECIFICATION | elmos Services BV |
| Author: ASto | 16 Lead Small Outline Package (300mil) (SO16w) | QM-No.: 08SP0660.07 |

Package Outline and Dimensions are according JEDEC MS-013-E, variant AA



| Description | Symbol | mm | | | inch | | |
|--|----------|-----------|-----|------|-----------|-----|-------|
| | | min | typ | max | min | typ | max |
| Package height | A | -- | -- | 2.65 | -- | -- | 0.104 |
| Stand off | A1 | 0.10 | -- | 0.30 | 0.004 | -- | 0.012 |
| Package body thickness | A2 | 2.05 | -- | -- | 0.081 | -- | -- |
| Width of terminal leads, inclusive lead finish | b | 0.31 | -- | 0.51 | 0.012 | -- | 0.020 |
| Thickness of terminal leads, inclusive lead finish | c | 0.20 | -- | 0.33 | 0.008 | -- | 0.013 |
| Package length | D | 10.30 BSC | | | 0.406 BSC | | |
| Package width | E | 10.30 BSC | | | 0.406 BSC | | |
| Package body width | E1 | 7.50 BSC | | | 0.295 BSC | | |
| Lead pitch | e | 1.27 BSC | | | 0.050 BSC | | |
| Length of terminal for soldering to substrate | L | 0.4 | -- | 1.27 | 0.016 | -- | 0.050 |
| body chamfer (45°) | h | 0.25 | -- | 0.75 | 0.010 | -- | 0.030 |
| Angle of lead mounting area | phi [°] | 0 | -- | 8 | 0 | -- | 8 |
| mold release angle | phi1 [°] | 5 | -- | 15 | 5 | -- | 15 |
| Number of terminal positions | N | 16 | | | 16 | | |

Note: the mm values are valid, the inch values contains rounding errors

Note 1: for assembler specific pin1 identification please see QM-document 08SP0363.xx (Pin 1 Specification)